

**AMENDMENTS TO THE CLAIMS:**

This listing of claims replaces the listing of claims in the Application.

Listing of Claims:

1-4. (Cancelled)

5. (Currently Amended)      A method for the production of an injection molded conductor carrying means with the use of a dual component injection molding method, in the case of which a first plastic material, which is in principle able to be metallized, and a second plastic material, which is in principle not able to be metallized but is able to be activated by a laser beam, are so formed or molded on each other that a substrate body is produced, which includes a first supporting substrate ~~consisting~~ comprised of the first plastic material and a second supporting substrate partially covering the first supporting substrate ~~consisting~~ comprised of the second plastic material, following which a ~~metallized~~ metallization pattern is produced on the second supporting substrate by laser beam activation, which pattern at least partially adjoins one or more uncovered areas of the first supporting substrate and following which a metallized layer is deposited simultaneously on the metallization pattern and on the uncovered areas, such metallized layer being able to be utilized as an electrical conductor arrangement.

6. (Currently Amended)      The method as set forth in claim 5, wherein the metallization pattern adjoins ~~pad-like~~ uncovered areas of large size on the first supporting substrate.

7. (Cancelled)